

INTERNATIONAL STANDARD

IEC 61249-3-4

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Materials for printed boards and other interconnecting structures –

Part 3-4: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) – Adhesive coated flexible polyimide film

*Matériaux pour circuits imprimés et autres structures
d'interconnexion –*

*Partie 3-4:
Collection de spécifications intermédiaires pour les matériaux
de base non renforcés, recouverts ou non
(prévus pour les circuits imprimés flexibles) –
Film flexible de polyimide recouvert de colle*

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International Electrotechnical Commission 3, rue de Varembe Geneva, Switzerland
Telefax: +41 22 919 0300 e-mail: inmail@iec.ch IEC web site <http://www.iec.ch>



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

Part 3-4: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) – Adhesive coated flexible polyimide film

FOREWORD

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International Standard IEC 61249-3-4 has been prepared by IEC technical committee 52: Printed circuits.

The text of this standard is based on the following documents:

FDIS	Report on voting
52/773/FDIS	52/798/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

Annex A is for information only.

A bilingual version of this standard may be issued at a later date.

MATERIALS FOR PRINTED BOARDS AND OTHER INTERCONNECTING STRUCTURES –

Part 3-4: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) – Adhesive coated flexible polyimide film

1 Scope

This part of IEC 61249 gives requirements for flexible polyimide films coated on one side or both sides with acrylic or epoxide type adhesive for use in the fabrication of flexible printed wiring.

Films coated on only one side are used as a coverlay or covercoat in the fabrication of flexible printed wiring. This coverlay or covercoat is also used to provide local support to areas subjected to mechanical or environmental stress.

Films coated on both sides are used as bonding films in the fabrication of printed boards.

2 Normative reference

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 61249. For dated references, subsequent amendments to, or revisions of, any of these publications do not apply. However, parties to agreements based on this part of IEC 61249 are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. For undated references, the latest edition of the normative document referred to applies. Members of IEC and ISO maintain registers of currently valid International Standards.

IEC 61189-2:1997, *Test methods for electrical materials, interconnection structures and assemblies – Part 2: Test methods for materials for interconnection structures*